



Material Content Data Sheet



Sales Product Name		SAL-XC866L-4FRA 3V BE		Issued		29. August 2013		
MA#		MA000914036						
Package		PG-TSSOP-38-4		Weight*		118.23 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.433	5.44	5.44	54413	54413
leadframe	non noble metal	magnesium	7439-95-4	0.075	0.06		636	
	inorganic material	silicon	7440-21-3	0.326	0.28		2757	
	non noble metal	nickel	7440-02-0	1.504	1.27		12724	
	non noble metal	copper	7440-50-8	48.239	40.80	42.41	408007	424124
	wire	noble metal	gold	7440-57-5	0.875	0.74	0.74	7404
encapsulation	organic material	carbon black	1333-86-4	0.176	0.15		1490	
	plastics	epoxy resin	-	7.460	6.31		63098	
	inorganic material	silicondioxide	60676-86-0	51.105	43.23	49.69	432244	496832
plating	noble metal	gold	7440-57-5	0.004	0.00		37	
	noble metal	silver	7440-22-4	0.002	0.00		20	
	noble metal	palladium	7440-05-3	0.003	0.00		23	
	non noble metal	nickel	7440-02-0	0.080	0.07	0.07	676	756
glue	plastics	epoxy resin	-	0.389	0.33		3294	
	noble metal	silver	7440-22-4	1.558	1.32	1.65	13177	16471
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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